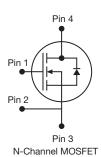
HALOGEN FREE



E Series Power MOSFET

| PRODUCT SUMMARY | | | | |
|--|------------------------------|--|--|--|
| V _{DS} (V) at T _J max. | 700 | | | |
| R _{DS(on)} typ. (Ω) at 25 °C | V _{GS} = 10 V 0.225 | | | |
| Q _g max. (nC) | 96 | | | |
| Q _{gs} (nC) | 12 | | | |
| Q _{gd} (nC) | 21 | | | |
| Configuration | Single | | | |





FEATURES

- Completely lead (Pb)-free device
- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (C_{iss})
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

| ORDERING INFORMATION | |
|---------------------------------|-------------------|
| Package | PowerPAK 8 x 8 |
| Lead (Pb)-free and Halogen-free | SiHH14N65E-T1-GE3 |

| ABSOLUTE MAXIMUM RATINGS (1 | √ _C = 25 °C, unl | ess otherwis | se noted) | | |
|---|-----------------------------|---|-----------------------------------|-------------|---------|
| PARAMETER | | | SYMBOL | LIMIT | UNIT |
| Drain-Source Voltage | | | V _{DS} | 650 | V |
| Gate-Source Voltage | | | V_{GS} | ± 30 | 7 ° |
| Continuous Drain Current (T _{.I} = 150 °C) | V _{GS} at 10 V | T _C = 25 °C T _C = 100 °C | - I _D | 15 | |
| Continuous Drain Current (1) = 150 C) | V _{GS} at 10 V | T _C = 100 °C | | 10 | Α |
| Pulsed Drain Current ^a | | | I _{DM} | 38 | |
| Linear Derating Factor | | | | 1.25 | W/°C |
| Single Pulse Avalanche Energy ^b | | | E _{AS} | 226 | mJ |
| Maximum Power Dissipation | | | P_{D} | 156 | W |
| Operating Junction and Storage Temperature Range | | | T _J , T _{stg} | -55 to +150 | °C |
| Drain-Source Voltage Slope T _J = 125 °C | | | dV/dt | 70 | V/ns |
| Reverse Diode dV/dt ^c | | | | 19 |) v/ris |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4 A.
- c. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.



Vishay Siliconix

| THERMAL RESISTANCE RATINGS | | | | | | |
|----------------------------------|------------|------|------|------|--|--|
| PARAMETER SYMBOL TYP. MAX. UNIT | | | | | | |
| Maximum Junction-to-Ambient | R_{thJA} | 42 | 55 | °C/W | | |
| Maximum Junction-to-Case (Drain) | R_{thJC} | 0.57 | 0.80 | C/VV | | |

| PARAMETER | SYMBOL | TES | T CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|--|--|------|-------|-------|------------|
| Static | | | | | | | • |
| Drain-Source Breakdown Voltage | V _{DS} | V _{GS} = | = 0 V, I _D = 250 μA | 650 | - | - | V |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | Referenc | e to 25 °C, I _D = 1 mA | - | 0.81 | - | V/°C |
| Gate-Source Threshold Voltage (N) | V _{GS(th)} | V _{DS} = | · V _{GS} , I _D = 250 μA | 2.0 | - | 4.0 | V |
| Cata Sauraa Laakaaa | I _{GSS} | , | V _{GS} = ± 20 V | | | ± 100 | nA |
| Gate-Source Leakage | | , | $V_{GS} = \pm 30 \text{ V}$ | - | =. | ± 1 | μΑ |
| Zava Cata Valta va Dusia Comunit | | V _{DS} = | 650 V, V _{GS} = 0 V | - | - | 1 | T . |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 520 V | , V _{GS} = 0 V, T _J = 125 °C | - | - | 50 | μA |
| Drain-Source On-State Resistance | R _{DS(on)} | V _{GS} = 10 V | $I_D = 7 A$ | - | 0.225 | 0.260 | Ω |
| Forward Transconductance | 9 _{fs} | V _{DS} | = 30 V, I _D = 7 A | - | 5.4 | - | S |
| Dynamic | | | | | | • | |
| Input Capacitance | C _{iss} | | $V_{GS} = 0 V$, | - | 1712 | - | |
| Output Capacitance | C _{oss} | , | V _{DS} = 100 V, | - | 85 | - | |
| Reverse Transfer Capacitance | C _{rss} | | f = 1 MHz | - | 2 | - | |
| Effective Output Capacitance, Energy Related ^a | C _{o(er)} | ., ., | //. 500 // // O // | - | 56 | - | pF |
| Effective Output Capacitance, Time Related ^b | C _{o(tr)} | $V_{DS} = 0$ | / to 520 V, V _{GS} = 0 V | - | 229 | - | |
| Total Gate Charge | Qq | | | - | 48 | 96 | |
| Gate-Source Charge | Q _{gs} | V _{GS} = 10 V | $I_D = 7 A, V_{DS} = 520 V$ | - | 12 | - | nC |
| Gate-Drain Charge | Q _{gd} | | | - | 21 | - | |
| Turn-On Delay Time | t _{d(on)} | | | - | 22 | 44 | |
| Rise Time | t _r | V _{DD} = 520 V, I _D = 7 A, | | - | 30 | 60 | |
| Turn-Off Delay Time | t _{d(off)} | | $= 10 \text{ V}, R_g = 9.1 \Omega$ | - | 53 | 80 | ns |
| Fall Time | t _f | | | - | 31 | 62 | |
| Gate Input Resistance | R_g | f = 1 | MHz, open drain | 0.35 | 0.70 | 1.4 | Ω |
| Drain-Source Body Diode Characteristic | s | | | | | | |
| Continuous Source-Drain Diode Current | I _S | showing the | MOSFET symbol showing the | | - | 15 | |
| Pulsed Diode Forward Current | I _{SM} | integral reverse p - n junction diode | | - | - | 38 | A |
| Diode Forward Voltage | V _{SD} | T _J = 25 ° | C, I _S = 7 A, V _{GS} = 0 V | - | 0.9 | 1.2 | V |
| Reverse Recovery Time | t _{rr} | | | - | 349 | 698 | ns |
| Reverse Recovery Charge | Q _{rr} | | $5 ^{\circ}\text{C}, I_F = I_S = 7 \text{A},$ | - | 4.4 | 8.8 | μC |
| Reverse Recovery Current | I _{RRM} | | 100 A/μs, V _R = 25 V | _ | 20 | - | A |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

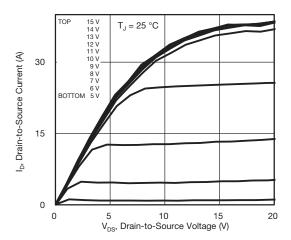


Fig. 1 - Typical Output Characteristics

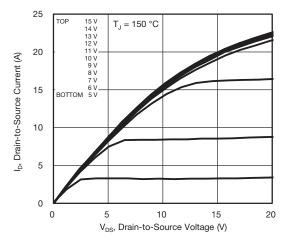


Fig. 2 - Typical Output Characteristics

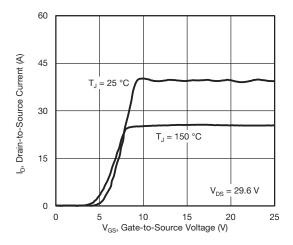


Fig. 3 - Typical Transfer Characteristics

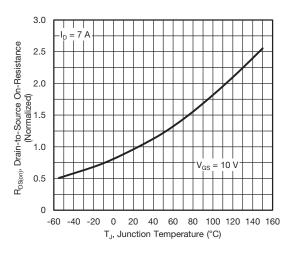


Fig. 4 - Normalized On-Resistance vs. Temperature

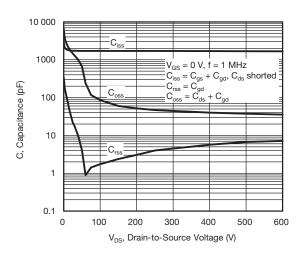


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

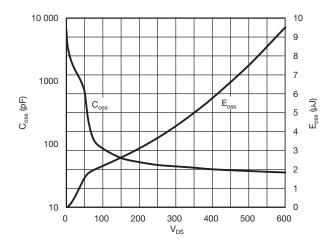


Fig. 6 - C_{OSS} and E_{OSS} vs. V_{DS}



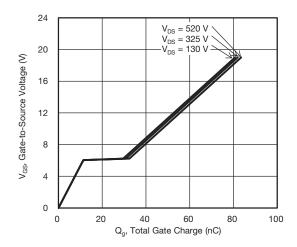


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

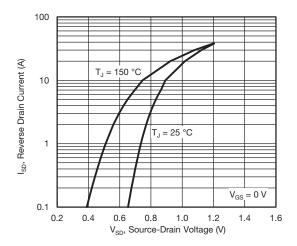


Fig. 8 - Typical Source-Drain Diode Forward Voltage

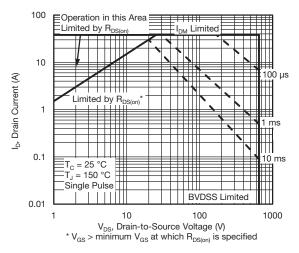


Fig. 9 - Maximum Safe Operating Area

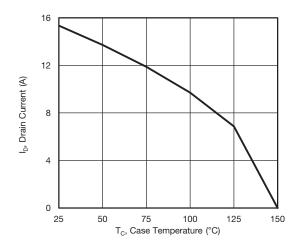


Fig. 10 - Maximum Drain Current vs. Case Temperature

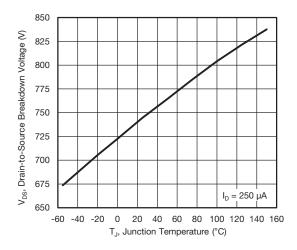


Fig. 11 - Temperature vs. Drain-to-Source Voltage



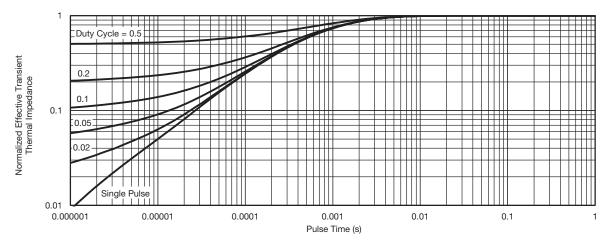


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

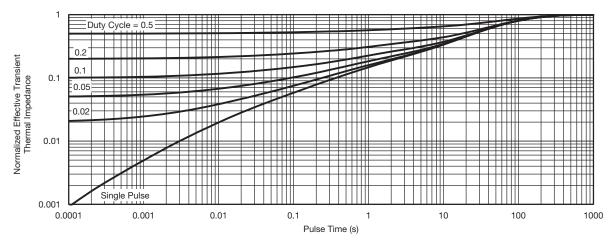


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

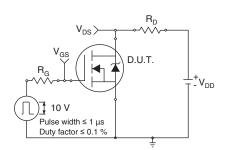


Fig. 14 - Switching Time Test Circuit

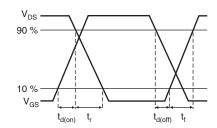


Fig. 15 - Switching Time Waveforms

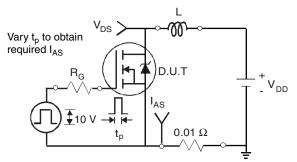


Fig. 16 - Unclamped Inductive Test Circuit

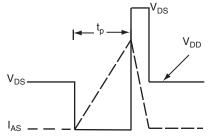
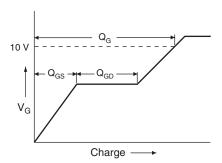


Fig. 17 - Unclamped Inductive Waveforms





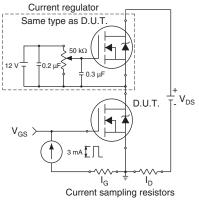
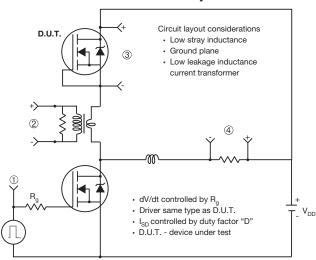


Fig. 18 - Basic Gate Charge Waveform

Fig. 19 - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



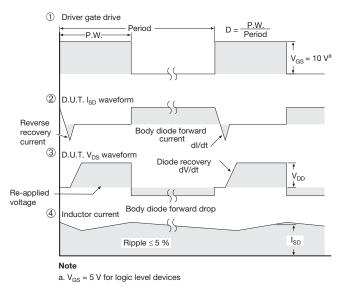


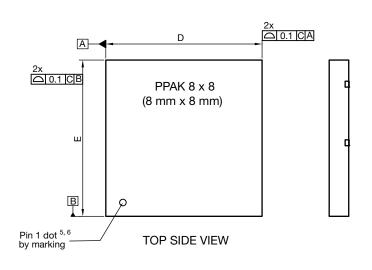
Fig. 20 - For N-Channel

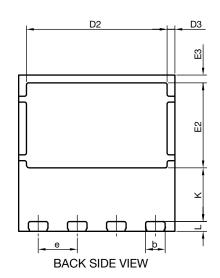
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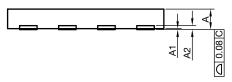


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PowerPAK® 8 x 8 Case Outline







| DIM | MILLIMETERS | | | INCHES | | | |
|------------------|-------------|----------|-----------|------------|-----------|-------|--|
| DIM. | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. | |
| Α | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 | |
| A1 | 0.00 | - | 0.05 | 0.000 | - | 0.002 | |
| A2 | 020 ref. | | | 0.008 ref. | | | |
| b | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 | |
| D | 7.90 | 8.00 | 8.10 | 0.311 | 0.315 | 0.319 | |
| D2 | 7.10 | 7.20 | 7.30 | 0.280 | 0.283 | 0.287 | |
| D3 | 0.40 BSC | | | 0.016 BSC | | | |
| е | 2.00 BSC | | 0.079 BSC | | | | |
| E | 7.90 | 8.00 | 8.10 | 0.311 | 0.315 | 0.319 | |
| E2 | 4.30 | 4.35 | 4.40 | 0.169 | 0.171 | 0.173 | |
| E3 | | 0.40 BSC | | | 0.016 BSC | | |
| K | 2.75 BSC | | 0.108 BSC | | | | |
| L | 0.45 | 0.50 | 0.55 | 0.018 | 0.020 | 0.022 | |
| N ⁽³⁾ | 8 | | | | 8 | | |

Notes

- (1) Use millimeters as the primary measurement
- (2) Dimensioning and tolerances conform to ASME Y14.5 M 1994
- (3) N is the number of terminals
- (4) The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
- (5) Exact shape and size of this feature is optional

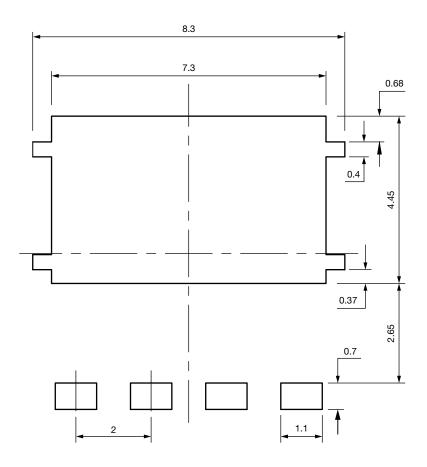
ECN: E20-0518-Rev. B, 28-Sep-2020

DWG: 6041

Revision: 28-Sep-2020 1 Document Number: 67859



Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



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